PCN Number:		20130321002					PCN Dat	:e:	04/10/2013	
Title: MSL level change for family of ADS78* devices in PW package										
		PCN N	<u>lanager</u>	Phone:	+1(214) 480-603		6037	7 Dept: Qua		ality Services
Propose	ed 1 st Ship Da	ite:	04/11/2013		stimated Sample A		vailability: 04/10/2		04/10/2013	
Change										
Assembly Site			Assembly Process					Assembly Materials		
Design			Electrical Specification Packing/Shipping/Labeling					Mechanical Specification		
Test Site			Packing/Shipping/Labeling				Test Process			
Wafer Bump Site				Wafer Bump Material				Wafer Bump Process		
Wafer Fab Site			Wafer	Wafer Fab Materials				Wafer Fab Process		
				PCN	Details	5				
Descrip	tion of Chang	je:								
Packa		<u> </u>				Cł	nang	ty ange To: el 1-260C		
2										
	for Change:	lified	to MSL 1							
Devices	have been qua									
Devices				unction,	Quality	or Reli	abil	ity (posit	ive ,	/ negative):
Devices	have been qua			unction,	Quality	or Reli	abil	ity (posit	ive ,	/ negative):
Devices Anticipa None	have been qua	on Fit,	Form, F					ity (posit	ive ,	/ negative):
Devices Anticipa None Change	have been qua	on Fit, identi	Form,	resulting	g from ti			ity (posit	ive ,	/ negative):
Devices Anticipa None Change Packing	have been qua ated impact o s to product	on Fit, identi	Form,	resulting	g from ti			ity (posit	ive ,	/ negative):
Devices Anticipa None Change Packing	have been qua ated impact o s to product label on bag, b t Affected:	identi	Form,	r esulting licate: 'M	g from ti	nis PCN	l:	ity (posit		
Devices Anticipa None Change Packing Product ADS782	have been qua ated impact o s to product label on bag, b t Affected:	identi	Form,	resulting licate: 'M	from tl S LVL: 1'	n is PCN 8EB/2K5	l:		301P	WRG4

Qualific	ation Data: Approv	ed 3/XX/2	013					
This qualification has been specifically				ion data				
validates that the proposed change n								
Qualification Device: ADS7830IPW (MSL 1-260C) Package Construction Details								
Assembly Site:	TI Malaysia	Mol	4206193					
# Pins-Designator, Family:	16-PW, TSSOP		NiPdAu					
Qualification: 🗌 Plan 🛛 🕇	Test Results							
Poliability Test	Conditions	Sample Size/Fail						
Reliability Test	Conditions	Lot#1	Lot#2					
**Unbiased HAST	130C/85%RH (96	78/0	80/0					
**T/C -65C/150C	-65C/+150C (500	77/0	80/0					
Manufacturability (Assembly)	(per mfg. Site speci	pass	pass					
Moisture Sensitivity	(level 1 @ 260C peak	pass	pass					
** - Test requires Moisture Precondit	ioning (MSL1-260C)							

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com